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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jean-Michel Daga et al. PATENT APPLICATION
Serial No.: 10/810,033 Group Art Unit: 2816
Filed: March 26, 2004 Examiner:
For: HIGH EFFICIENCY, LOW COST, CHARGE PUMP CIRCUIT

Supplemental Information Disclosure Statement

Hon. Commissioner for Patents
Alexandria, VA 22313

Sir:

The following information is submitted in compliance with Applicants' duty of disclosure under 37 CFR § 1.56. A copy of the reference is enclosed.

Other Reference

Hongchin Lin et al., "New Four-Phase Generation Circuits for Low-Voltage Charge Pumps", IEEE, 2001, pp. 504-507.

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Asst. Commissioner for Patents, Alexandria, VA 22313

Signed: Sally Azevedo
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Date: June 21, 2004

Respectfully submitted,

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FORM PTO-1449		Atty. Docket No. ATM-276	Serial No. 10/810,033
LIST OF PRIOR ART CITED BY APPLICANT		Applicant: Jean-Michel Daga et al.	
		Filing Date: March 26, 2004	Group: 2816

U.S. PATENT DOCUMENTS

Examiner Initial*	Document Number	Grant Date	Name	Class	Sub Class	Filing Date
AA						
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FOREIGN PATENT DOCUMENTS

Examiner Initial*	Document Number	Grant Date	Country	Class	Sub Class	Translation Yes No
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AL						

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AM	Hongchin Lin et al., "New Four-Phase Generation Circuits for Low-Voltage Charge Pumps", IEEE, 2001, pp. 504-507.
AN	
AO	

EXAMINER:

DATE CONSIDERED:

*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.